

SlimPAQ

Material Content Declaration					
Material name	Substance name, e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 59.23%	Copper (Cu)	7440-50-8	153.7228	99.82	591,241.5
	Iron (Fe)	7439-89-6	0.2310	0.15	888.5
	Phosphorus(P)	7723-14-0	0.0462	0.03	177.7
	Total		154		
Solder Paste 1.92%	Lead (Pb)	7439-92-1	4.625	92.5	17,788.5
	Tin (Sn)	7440-31-5	0.250	5.0	961.5
	Silver (Ag)	7440-22-4	0.125	2.5	480.8
	Total		5.0		
Chip 2.69%	Silicon (Si)	7440-21-3	6.749	96.41	25,957.7
	Aluminum (Al)	7429-90-5	0.140	2.00	538.5
	Silver (Ag)	7440-22-4	0.070	1.00	269.2
	Nickel (Ni)	7440-02-0	0.006	0.09	23.1
	Tin (Sn)	7440-31-5	0.035	0.50	134.6
	Total		7.0		
Molding 34.62%	Silica (SiO ₂)	14808-60-7	67.50	75.00	259,615.4
	Aluminum hydroxide	21645-51-2	6.75	7.50	25,961.5
	Epoxy resin	29690-82-2	9.00	10.00	34,615.4
	Phenolic resin	9003-35-4	6.30	7.00	24,230.8
	Carbon Black	1333-86-4	0.45	0.50	1,730.8
	Total		90		
Plating 1.54%	Tin (Sn)	7440-31-5	4.0	100.00	15,384.6
	Total		4.0		
	Total mass (mg)		260.00		